

Update Notification
Document #: FPCN16200X1
Issue Date: 2 October 2015

Title of Change:	Phase 2 Copper Wire for VHVIC Products in SOIC and TSSOP packages in Carmona, Philippines
Proposed first ship date:	21 December 2015
Contact information:	Contact your local ON Semiconductor Sales Office or <scott.brow@onsemi.com></scott.brow@onsemi.com>
Samples:	Contact your local ON Semiconductor Sales Office or <scott.brow@onsemi.com></scott.brow@onsemi.com>
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office or <ken.fergus@onsemi.com>.</ken.fergus@onsemi.com>
Type of notification:	ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact <pcn.support@onsemi.com>.</pcn.support@onsemi.com>
Change category:	☐ Wafer Fab Change ☐ Assembly Change ☐ Test Change ☐ Other
Change Sub-Category(s): ☐ Datasheet/Product Doc change ☐ Manufacturing Site Change/Addition ☐ Material Change ☐ Shipping/Packaging/Marking ☐ Manufacturing Process Change ☐ Product specific change ☐ Other:	
Sites Affected: All site(s) not applicable ON Semiconductor site(s): External Foundry/Subcon site(s) ON Carmona, Philippines	
Description and Purpose:	
The devices listed in this FPCN were released to production after FPCN16200 was released to customers and prior to the factory conversion to Cu wire which will occur on 9/28/15. In order to give customers adequate time to evaluate the products listed in this Update Notification, these products will not convert to Cu wire until 12/21/15. A reliability summary supporting this change can be found in FPCN16200 and can be provided upon request.	
List of affected Standard Parts:	
NCP1240AD065R2G NCP1240BD100R2G NCP1240FD065R2G NCP1248AD065R2G NCP1248AD100R2G NCP1236ED100R2G NCP1236ED100R2G	

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